

METHOD AND APPARATUS FOR DIRECTLY
JOINING A CHIP TO A HEAT SINK

ABSTRACT OF THE DISCLOSURE

5 The present invention relates generally to a new
apparatus and method for directly joining a chip to a
heat sink. More particularly, the invention encompasses
an apparatus and a method that uses a double-sided,
pressure-sensitive, thermally-conductive adhesive tape to
10 directly join a chip or similar such device to a heat
sink.